

19 December 2024

CAPITAL RAISING UPDATE

4DS Memory Limited (ASX:4DS) (**4DS**) (the **Company**) provides an update in relation to its planned capital raising initiatives.

After consultation with various parties, the Company has elected not to proceed with a capital raise because the offering wasn't reflective of what the Board considers is in the best interest of shareholders.

The Company intends to raise capital in early 2025 to enable it to fund its obligations under the Design Agreement it has recently entered into with Infineon Technologies LLC, which will design a custom ReRAM memory test chip for 4DS. As announced previously, the funds due under the Design Agreement will be paid progressively over 15 months, being the term of the agreement.

The Company will provide an update in January 2025 in relation to the nature and size of its planned capital raising activities and endeavor to make sure existing shareholders will have the right to participate.

4DS Interactive Investor Hub

If you have any questions on this announcement or any past 4DS announcements, check out our Investor Hub.

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Authorised for release by the Board.

ENDS

Contact information

Investors: David McAuliffe
Executive Chairman
4DS Memory
+61 408 994 313
david@4dsmemory.com

About 4DS

4DS Memory Limited (ASX: 4DS), with facilities located in Silicon Valley, is a semiconductor technology company bringing high bandwidth, high endurance, persistent non-volatile memory to advanced CMOS process nodes. Its technology, known as Interface Switching ReRAM, features tunable persistence and low energy per bit for today's most challenging compute intensive and AI processor applications. Established in 2007, 4DS owns a patented IP portfolio, comprising 34 USA patents, and is the first company to develop PCMO ReRAM, on an advanced CMOS processing node. 4DS has a development agreement with Belgium based imec – a world leading research and innovation hub in nano electronics and digital technologies, as well as a joint development agreement with Western Digital subsidiary HGST, a global leader in storage solutions.

For more information, please visit www.4dsmemory.com.

Disclaimer

This release contains certain forward-looking statements that are based on the Company's management's beliefs, assumptions and expectations and on information currently available to management. Such forward looking statements involve known and unknown risks, uncertainties, and other factors which may cause the actual results or performance of 4DS to be materially different from the results or performance expressed or implied by such forward looking statements. Such forward looking statements are based on numerous assumptions regarding the Company's present and future business strategies and the political and economic environment in which 4DS will operate in the future, which are subject to change without notice. Past performance is not necessarily a guide to future performance and no representation or warranty is made as to the likelihood of achievement or reasonableness of any forward-looking statements or other forecast. To the full extent permitted by law, 4DS and its directors, officers, employees, advisers, agents and intermediaries disclaim any obligation or undertaking to release any updates or revisions to information to reflect any change in any of the information contained in this release (including, but not limited to, any assumptions or expectations set out in the release).

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